

Strain Gage Adhesive



OTHER ACCESSORIES USED IN AN M-BOND GA-2 INSTALLATION:

- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- PCT-2M Gage Installation Tape
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION

Two-component, partially filled, 100%-solids epoxy system for general-purpose stress analysis. Higher viscosity than AE systems. Elevated-temperature cure recommended for best

performance and resistance to chemical attack. Often used to fill irregular surfaces. Uneven gluelines easily detectable by nonuniformity of bond color.

CHARACTERISTICS

Operating Temperature Range:

Long Term: -320° to +200°F [-195° to +95°C].

Elongation Capabilities:

4% at -320°F [-195°C].

10% to 15% at +75°F [+24°C] after 40-hour RT cure or 6-hour RT cure with postcure.

Shelf Life:

12 months at +75°F [+24°C]; 18 months at +20°F [-7°C].

Pot Life:

15 minutes at +75°F [+24°C]. Can be extended by cooling jar or by spreading adhesive on clean aluminum plate.

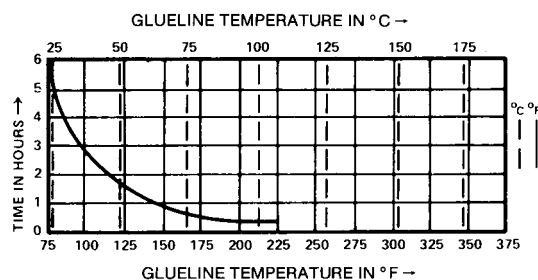
Clamping Pressure:

5 to 20 psi [35 to 140 kN/m²]. The black filler provides a visual indication of nonuniform bond areas caused by uneven clamping pressure.

Cure Requirements:

Preferred Room-Temperature Cure: 40 hours at +75°F [+24°C].

Recommended Postcure: 2 hours at 25°F [15°C] above maximum operating temperature.



PACKAGING

Kit:

- 6 mixing jars [15 g ea] Resin
- 6 calibrated pipettes
- 1 bottle [15 ml] Curing Agent 10-A
- 6 stirring rods

References: Instruction Bulletin B-137, "Strain Gage Applications with M-Bond AE-10, AE-15, and GA-2 Adhesive Systems," included in each kit.